, [L Number	Hits	Search Text	DB	Time stamp
Γ	1	2	5426072.pn.	USPAT;	2004/04/01
				US-PGPUB;	15:32
				EPO; JPO;	
-	_			DERWENT	
	2	91	5426072.URPN.	USPAT	2004/04/01
	3	7	/#3603081# #3633310# #4033037#	110 D B M	15:32
	3	,	("3602981" "3623219" "4022927" "4423435" "4980308" "5244817"	USPAT	2004/04/01 16:19
			"5279991").PN.		10.19
	4	130	((((three adj dimensional) or	USPAT;	2004/04/01
	_		"three-dimensional" or "3d") with	US-PGPUB;	16:33
			((integrated adj circuit) or ic)) and	EPO; JPO;	•
			438/\$3.ccls. and @ad<19990423) and	DERWENT	
			((thin\$4 or remov\$3) with substrate) and		
	_	22	soi		2004/04/01
	5	22	((three adj dimensional) or "three-dimensional" or "3d") same (soi or	USPAT; US-PGPUB;	2004/04/01 16:46
١			(silicon adj3 insulat\$3)) same	EPO; JPO;	10:40
			(interconnect or vertical) and	DERWENT	
			(@ad<19990423 or @rlad<19990423)	DEKWENT	
	6	2423	((three adj dimensional) or	USPAT;	2004/04/01
-			"three-dimensional" or "3d") and (soi or	US-PGPUB;	16:47
1			(silicon adj3 insulat\$3)) and ((thin\$4 or	EPO; JPO;	
		:	etch\$3 or remov\$3) with substrate) and	DERWENT	
	8	12	(@ad<19990423 or @rlad<19990423) (((three adi dimensional) or	USPAT;	2004/04/01
	0	12	"three-dimensional" or "3d") and (soi or	US-PGPUB;	16:50
			(silicon adj3 insulat\$3)) and ((thin\$4 or	EPO; JPO;	10.00
			etch\$3 or remov\$3) with substrate) and	DERWENT	
			(@ad<19990423 or @rlad<19990423)) and		
			interconnect and 438/459.ccls.		
	7	260	(((three adj dimensional) or	USPAT;	2004/04/01
			"three-dimensional" or "3d") and (soi or	US-PGPUB;	17:00
			<pre>(silicon adj3 insulat\$3)) and ((thin\$4 or etch\$3 or remov\$3) with substrate) and</pre>	EPO; JPO; DERWENT	
			(@ad<19990423 or @rlad<19990423)) and	DEKNIGHT	
			interconnect and 438/\$3.ccls.		
	-	0		USPAT;	2004/04/01
			fox) and (thin\$4 with backside with	US-PGPUB;	15:32
			substrate) and (backside with (connection	EPO; JPO;	
		124	or contact)) soi and (via hole open\$3 contact) and	DERWENT USPAT;	2003/10/09
ŀ	_	124	(thin\$4 with substrate) and (backside	US-PGPUB;	15:06
			with (connection or contact))	EPO; JPO;	10.00
			· · · · · · · · · · · · · · · · · · ·	DERWENT	
	-	75	(USPAT;	2003/04/24
			(thin\$4 with substrate) and (backside	US-PGPUB;	14:41
			with (connection or contact))) and	EPO; JPO;	
	_	69	<pre>@ad<19990423 soi and (via hole open\$3 contact) and</pre>	DERWENT USPAT;	2003/04/24
-		69	(backside with etch\$3) and (backside with	US-PGPUB;	14:54
			(connection or contact))	EPO; JPO;	=
	į		,	DERWENT	
	-	41	(soi and (via hole open\$3 contact) and	USPAT;	2003/04/24
			(backside with etch\$3) and (backside with	US-PGPUB;	15:00
			(connection or contact))) and	EPO; JPO;	
	_	36	<pre>@ad<19990423 (form\$3 with (via hole open\$3 contact)</pre>	DERWENT USPAT;	2003/10/09
		36	with (field adj oxide)) and (backside	US-PGPUB;	15:09
			with etch\$3)	EPO; JPO;	
			····	DERWENT	
	-	25	((form\$3 with (via hole open\$3 contact)	USPAT;	2003/04/24
			with (field adj oxide)) and (backside	US-PGPUB;	15:23
			with etch\$3)) and @ad<19990423	EPO; JPO;	
	_	2	5426072.pn.	DERWENT USPAT;	2003/04/24
		2	0420072.pm.	US-PGPUB;	15:23
				EPO; JPO;	
				DERWENT	

-	106	<pre>soi and (vertical with interconnect) and field and (substrate with (etch\$3 or remov\$3))</pre>	USPAT; US-PGPUB; EPO; JPO;	2003/10/09 15:10
-	45	(soi and (vertical with interconnect) and field and (substrate with (etch\$3 or	DERWENT USPAT; US-PGPUB;	2003/04/25 15:04
		remov\$3))) and @ad<19990423	EPO; JPO; DERWENT	
-	2559	<pre>((three adj dimensional) or "three-dimensional") with ((integrated adj circuit) or ic)</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/10/09 14:41
-	404	(((three adj dimensional) or "three-dimensional") with ((integrated adj circuit) or ic)) and 438/\$3.ccls. and @ad<19990423	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/10/08 18:19
-	124	<pre>((((three adj dimensional) or "three-dimensional") with ((integrated adj circuit) or ic)) and 438/\$3.ccls. and @ad<19990423) and ((thin\$4 or remov\$3) with substrate) and soi</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/04/01 16:22
-	26	(((((three adj dimensional) or "three-dimensional") with ((integrated adj circuit) or ic)) and 438/\$3.ccls. and (@ad<19990423) and ((thin\$4 or remov\$3) with substrate) and soi) and ((back or rear) adj side)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/10/08 18:20
-	69	((vertical\$2 or vertigal) adj integration) and 438/\$3.ccls. and @ad<19990423	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/10/08 18:34
-	0	((((vertical\$2 or vertigal) adj integration) and 438/\$3.ccls. and @ad<19990423) and ((thin\$4 or remov\$3) with substrate) and soi) and ((back or rear) adj side)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/10/08 18:35
-	13	<pre>(((vertical\$2 or vertigal) adj integration) and 438/\$3.ccls. and @ad<19990423) and ((thin\$4 or remov\$3) with substrate) and soi</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/10/08 18:35
-	136	((vertical\$2 or vertigal) adj integrat\$4) and 438/\$3.ccls. and @ad<19990423	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/10/08 18:34
-		((vertical\$2 or vertigal) adj integratable) and 438/\$3.ccls. and @ad<19990423	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/10/08 18:34
-	3	(((vertical\$2 or vertigal) adj integrat\$4) and 438/\$3.ccls. and @ad<19990423) and ((back or rear) adj side)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/10/08 18:35
-		<pre>((((vertical\$2 or vertigal) adj integrat\$4) and 438/\$3.ccls. and @ad<19990423) and ((back or rear) adj side)) and ((thin\$4 or remov\$3) with substrate) and soi</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/10/08 18:36
-	25	(((vertical\$2 or vertigal) adj integrat\$4) and 438/\$3.ccls. and @ad<19990423) and ((thin\$4 or remov\$3) with substrate) and soi	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/10/08 18:36
-	3347	(438/618 or 438/620 or 438/637 or 438/667 or 438/672 or 438/675).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/10/09 14:41
-	2559	<pre>((three adj dimensional) or "three-dimensional") with ((integrated adj circuit) or ic)</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/10/09 14:42

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-	42	((438/618 or 438/620 or 438/637 or	USPAT;	2003/10/09
		438/667 or 438/672 or 438/675).ccls.) and	US-PGPUB;	14:42
		(((three adj dimensional) or	EPO; JPO;	
		"three-dimensional") with ((integrated	DERWENT	
		adj circuit) or ic))		
-	24	(((438/618 or 438/620 or 438/637 or	USPAT;	2003/10/09
		438/667 or 438/672 or 438/675).ccls.) and	US-PGPUB;	15:15
		(((three adj dimensional) or	EPO; JPO;	
		"three-dimensional") with ((integrated	DERWENT	
		adj circuit) or ic))) and @ad<19990423		
-	134	soi and (via hole open\$3 contact) and	USPAT;	2003/10/09
		(thin\$4 with substrate) and (backside	US-PGPUB;	15:06
		with (connection or contact))	EPO; JPO;	
			DERWENT	
-	3	((438/618 or 438/620 or 438/637 or	USPAT;	2003/10/09
		438/667 or 438/672 or 438/675).ccls.) and	US-PGPUB;	15:09
		(soi and (via hole open\$3 contact) and	EPO; JPO;	
		(thin\$4 with substrate) and (backside	DERWENT	
		with (connection or contact)))		
-	39	(= ·=··· · · · · · · · · · · · · · · ·	USPAT;	2003/10/09
		with (field adj oxide)) and (backside	US-PGPUB;	15:09
		with etch\$3)	EPO; JPO;	
			DERWENT	/ /
-	2		USPAT;	2003/10/09
		438/667 or 438/672 or 438/675).ccls.) and	US-PGPUB;	15:10
		((form\$3 with (via hole open\$3 contact)	EPO; JPO;	
		with (field adj oxide)) and (backside	DERWENT	
	112	with etch\$3))	110555	2002 (10 (00
-	113		USPAT; US-PGPUB;	2003/10/09
-		field and (substrate with (etch\$3 or	EPO; JPO;	15:10
		remov\$3))	DERWENT	
1_	10	((438/618 or 438/620 or 438/637 or	USPAT;	2003/10/09
_		438/667 or 438/672 or 438/675).ccls.) and	US-PGPUB;	15:15
		(soi and (vertical with interconnect) and	EPO; JPO;	13.13
		field and (substrate with (etch\$3 or	DERWENT	
		remov\$3)))		
_	73	1	USPAT;	2003/10/09
	, ,	438/667 or 438/672 or 438/675).ccls.) and	US-PGPUB;	15:15
1		((thin\$3 or remov\$3) with substrate) and	EPO; JPO;	
İ		soi	DERWENT	
_	28		USPAT;	2003/10/09
1		438/667 or 438/672 or 438/675).ccls.) and	US-PGPUB;	15:15
		((thin\$3 or remov\$3) with substrate) and	EPO; JPO;	
		soi) and @ad<19990423	DERWENT	